## PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
SHIFANG LI	09/13/2007
HANYOU CHU	09/17/2007

### **RECEIVING PARTY DATA**

Name:	Tokyo Electron Limited	
Street Address:	3-6 Akasaka 5-chome	
City:	Minato-Ku Tokyo	
State/Country:	JAPAN	
Postal Code:	107-8481	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11858882

## **CORRESPONDENCE DATA**

Fax Number: (480)539-2100

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 408-200-1431

Email: Manuel.Madriaga@us.tel.com
Correspondent Name: Manuel Barroga Madriaga
Address Line 1: 2953 Bunker Hill Lane Suite 301
Address Line 4: Santa Clara, CALIFORNIA 95054

ATTORNEY DOCKET NUMBER: TTI-177

NAME OF SUBMITTER: Manuel Barroga Madriaga

Total Attachments: 2

source=TTI-177-TYPE-assign#page1.tif source=TTI-177-TYPE-assign#page2.tif

H \$40.0

PATENT REEL: 019856 FRAME: 0819

## ASSIGNMENT OF INVENTION AND PATENTS THEREON

For valuable consideration, I/we, SHIFANG LI, hereby assign to Tokyo Electron Limited, a Corporation of Japan and having a place of business at TBS Broadcast Center, 3-6 Akasaka 5-chome, Minato-Ku, Tokyo 107-8481 JAPAN, and its successors and assigns (collectively hereinafter called "the Assignee"), my entire right, title and interest throughout the world in the inventions and improvements which are subject of an application of United States Patent entitled DETERMINING PROFILE PARAMETERS OF A STRUCTURE FORMED ON A SEMICONDUCTOR WAFER USING A DISPERSION FUNCTION RELATING PROCESS PARAMETER TO **DISPERSION**, and filed on **September 20**, **2007** as Patent Application No. 11 858 882, preparatory to obtaining Letters Patent of the United States therefore, this assignment including said application, any continuation, division or continuation-in-part thereof and/or substituted therefore, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and agree for myself and my heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications. assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment. I hereby authorize and request that any one of the attorneys or agents of Tokyo Electron U.S. Holdings, 2400 Grove Boulevard, Austin, Texas 78741, to insert herein the filing date and application serial number of said application when known.

Inventor's Signature: Milary W	_ Date: _	9/13/07	
Full Name: SHIFANG LI		1	
Residence: 5043 Rigatti Circle, Pleasanton, CA 94588			

# **ASSIGNMENT OF INVENTION AND PATENTS THEREON**

For valuable consideration, I/we, HANYOU CHU, hereby assign to Tokyo Electron Limited, a Corporation of Japan and having a place of business at TBS Broadcast Center, 3-6 Akasaka 5-chome, Minato-Ku, Tokyo 107-8481 JAPAN, and its successors and assigns (collectively hereinafter called "the Assignee"), my entire right, title and interest throughout the world in the inventions and improvements which are subject of an application of United States Patent entitled **DETERMINING PROFILE** PARAMETERS OF A STRUCTURE FORMED ON A SEMICONDUCTOR WAFER USING A DISPERSION FUNCTION RELATING PROCESS PARAMETER TO **DISPERSION**, and filed on **September 20**, **2007** as Patent Application No. 11 258882 preparatory to obtaining Letters Patent of the United States therefore, this assignment including said application, any continuation, division or continuation-in-part thereof and/or substituted therefore, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, and design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements: and agree for myself and my heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment. I hereby authorize and request that any one of the attorneys or agents of Tokyo Electron U.S. Holdings, 2400 Grove Boulevard, Austin, Texas 78741, to insert herein the filing date and application serial number of said application when known.

Inventor's Signature:	
Full Name: HANYOU CHU	
Residence: 4154 Frandon Ct, Palo Alto, CA 94306	

TTI-177

RECORDED: 09/20/2007 REEL: 019856 FRAME: 0821